

APR 03 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 3700**  
Kazushi HIGASHI et al. : **Docket No 2001\_0055**  
Serial No. 09/768,246 : **Group Art Unit 2811**  
Filed January 25, 2001 : **Examiner N. Parekh**

**METHOD OF FORMING A BALL BOND  
USING A BONDING CAPILLARY**

**AMENDMENT**

Assistant Commissioner for Patents,  
Washington, D.C.

Sir:

In response to the Office Action of October 4, 2002, the period for response to which having been extended by three months to April 4, 2003, please amend the above-identified U.S. Patent application as follows:

**IN THE SPECIFICATION**

**Please amend the specification as follows:**

**Please replace the paragraph beginning at page 4, line 7, with the following rewritten paragraph:**

Q1 According to a second aspect of the present invention, there is provided a method of forming a bump electrode on an IC electrode comprising: forming a ball bond portion on an IC electrode by a wire bonding apparatus; moving a bonding capillary upward; moving the bonding capillary sideways and then downward; bonding a wire to the ball bond portion; and cutting the wire, the wire being prevented from coming in contact with a periphery of the ball bond portion other than the ball bond portion itself by setting a chamfer angle of the bonding capillary not greater than 90 degrees to make the ball bond portion have a height greater than a diameter of the wire.